

ABSTRACT OF THE DISCLOSURE

Embodiments of the invention provide a method and apparatus for processing a substrate. The apparatus includes a substrate rinse cell configured to dispense a heated processing fluid onto the substrate prior to an annealing process. The method includes plating a conductive layer onto a substrate, heating the substrate in a cleaning cell via application of a heated cleaning fluid to the substrate, drying the substrate in the cleaning cell, and annealing the substrate at an annealing station at a temperature of between about 150°C and about 450°C.

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